

#### **Description**

The AP2318 is a series of ultra low dropout regulators optimized for low voltage applications where transient response and minimum input voltage are critical.

The AP2318 provides current limit and thermal shutdown. Its circuit includes a trimmed bandgap reference to assure output voltage accuracy to be within ±1.5%. On-chip thermal shutdown provides protection against any combination of overload and ambient temperatures that would create excessive junction temperatures.

The AP2318 has both fixed and adjustable versions. The 1.3V fixed versions integrate the corresponding resistor divider. The adjustable version can set the output voltage through two external resistors.

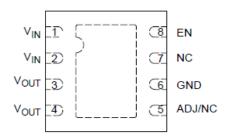
The AP2318 is available in the standard DFN-3x3-8 and SOIC-8 packages.

#### **Features**

- Wide Operating Voltage Ranges: 2.5V to 12V
- Output Voltage Accuracy: ±1.5%
- On-chip Thermal Shutdown
- ESD
  - Human Body Model 3kV
  - Machine Model 600V
- Operating Junction Temperature: -40°C to +125°C

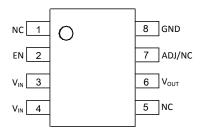
#### **Pin Assignments**

#### (Top View)



DFN-3x3-8

#### (Top View)



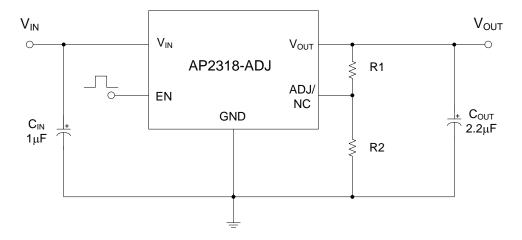
SOIC-8

#### **Applications**

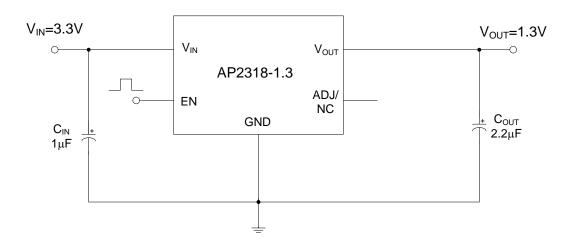
- Notebook
- USB Device
- Add-on CardDVD Player
- PC Motherboard



### **Typical Applications Circuit**



ADJ Version,  $V_{OUT} = 0.8*(R1+R2)/R2$ 



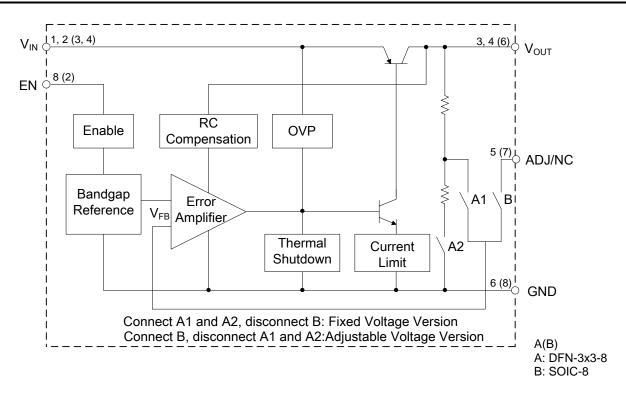
Fixed 1.3V Version, V<sub>OUT</sub> = 1.3V

### **Pin Description**

Pin Number				
DFN-3x3-8	SOIC-8	Pin Name	Function	
1, 2	3, 4	V <sub>IN</sub>	Input Voltage	
3, 4	6	Vout	Output Voltage	
5	7	ADJ/NC	Adjust Voltage/No Connection	
6	8	GND	Ground	
7	1, 5	NC	No Connection	
8	2	EN	On/Off Control	



#### **Functional Block Diagram**



#### Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rat	Unit		
V <sub>IN</sub>	Input Voltage	1	V		
TJ	Operating Junction Temperature	+150		°C	
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C	
T <sub>LEAD</sub>	Lead Temperature (Soldering, 10sec)	+260		°C	
ӨЈА		SOIC-8	135	°C/W	
	Thermal Resistance (Note 2)	DFN-3x3-8	120		
ESD	ESD (Human Body Model)	3000		V	
ESD	ESD (Machine Model)	600		V	

Notes: 1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

2. Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its operating ratings. The maximum allowable power dissipation is a function of the maximum junction temperature, T<sub>J</sub>(max), the junction-to-ambient thermal resistance, θ<sub>JA</sub>, and the ambient temperature, T<sub>A</sub>. The maximum allowable power dissipation at any ambient temperature is calculated using: P<sub>D</sub>(max) = (T<sub>J</sub>(max)-T<sub>A</sub>)/θ<sub>JA</sub>. Exceeding the maximum allowable power dissipation will result in excessive die temperature, and the regulator will go into thermal shutdown.



#### **Recommended Operating Conditions**

Symbol	Parameter	Min	Max	Unit
V <sub>IN</sub>	Input Voltage	2.5	12	V
V <sub>EN</sub>	Enable Voltage	_	12	V
TJ	Operating Junction Temperature Range	-40	+125	°C

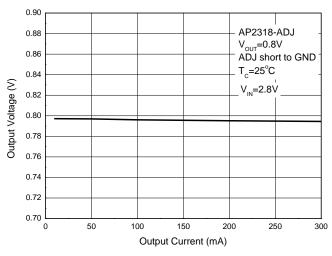
**Electrical Characteristics** (Operating Conditions:  $2.5\text{V} \le \text{V}_{\text{IN}} \le 12\text{V}$ ,  $C_{\text{IN}} = 1\mu\text{F}$ ,  $C_{\text{OUT}} = 2.2\mu\text{F}$ ,  $T_{\text{J}} = +25^{\circ}\text{C}$ , unless otherwise specified. (P  $\le$  Maximum Power Dissipation). Limits appearing in **Boldface** type apply over the entire junction temperature range for operation of  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{REF}$	Reference Voltage	AP2318-ADJ $I_{OUT} = 10$ mA, $V_{IN}-V_{OUT} = 2$ V, $T_{J} = +25$ °C $10$ mA $\leq I_{OUT} \leq 600$ mA, $V_{OUT}+2$ V $\leq V_{IN} \leq 12$ V		0.800 <b>0.800</b>	0.812 <b>0.816</b>	V
V <sub>OUT</sub>	Output Voltage	$I_{OUT} = 10$ mA, $V_{IN} = 2.5$ V, $T_{J} = +25$ °C $10$ mA $\leq I_{OUT} \leq 600$ mA, $2.5$ V $\leq V_{IN} \leq 12$ V		_	1.5% <b>2%</b>	V
I <sub>OUT</sub> (max)	Maximum Output Current	V <sub>IN</sub> -V <sub>OUT</sub> = 2V	0.85	1.2	_	Α
V <sub>RLINE</sub>	Line Regulation	AP2318-ADJ I <sub>OUT</sub> = 10mA, V <sub>OUT</sub> +2V ≤ V <sub>IN</sub> ≤ 12V		1	6	mV
KENVE		$I_{OUT} = 10$ mA, $2.5$ V $\leq V_{IN} \leq 12$ V	_	1	6	mV
V <sub>RLOAD</sub> Load Regulation	Load Regulation	AP2318-ADJ $V_{IN} = V_{OUT}+2V$ , $10mA \le I_{OUT} \le 600mA$	_	1	10	mV
REORD		V <sub>IN</sub> = 2.5V, 10mA ≤ I <sub>OUT</sub> ≤ 600mA	_	1	10	mV
$V_{DROP}$	Dropout Voltage	$\Delta V_{OUT} (\Delta V_{REF}) = 1\%$ , $I_{OUT} = 600$ mA		0.35	_	V
I <sub>ADJ</sub>	Adjust Pin Current	_		0.05	1	μΑ
I <sub>LOAD</sub> (min)	Minimum Load Current	V <sub>OUT</sub> +2V ≤ V <sub>IN</sub> ≤ 12V (ADJ only)		1.7	5	mA
IQ	Quiescent Current	V <sub>IN</sub> = V <sub>OUT</sub> +2V, I <sub>OUT</sub> = 0mA		250	_	μΑ
V <sub>NOI</sub>	RMS Output Noise (% of V <sub>OUT</sub> )	T <sub>A</sub> = +25°C, 10Hz ≤ f ≤ 20kHz		0.003	_	%
_	Thermal Shutdown Temperature	_	_	+150	_	°C
_	Thermal Shutdown Hysteresis	_	_	+25	_	°C
V <sub>EN</sub>	Enable Input Voltage	Enable Logic Low	_	_	0.8	
		Enable Logic High	2.25		_	V
I <sub>EN</sub>	Enable Input Current	V <sub>EN</sub> = 2.25V	_	5	15	μA
		V <sub>EN</sub> = 0.8V		_	4	μΑ
	Thermal Resistance	DFN-3x3-8	_	15	_	°C/W
θυс	(Junction to Case)	SOIC-8	_	24	_	

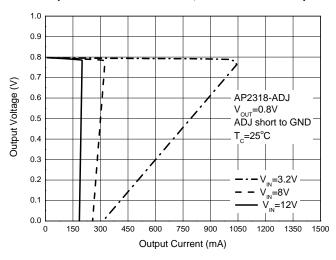


#### **Performance Characteristics**

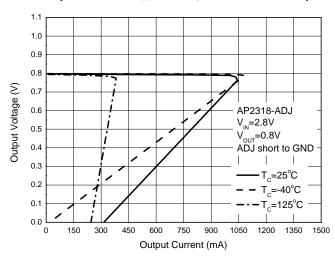
# Output Voltage vs. Output Current (Conditions: $V_{OUT} = 0.8V$ , ADJ Short to GND)



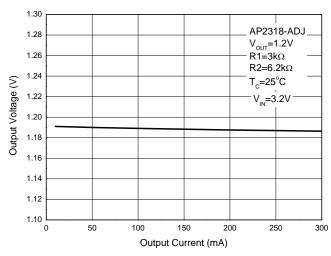
### Output Voltage vs. Output Current (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



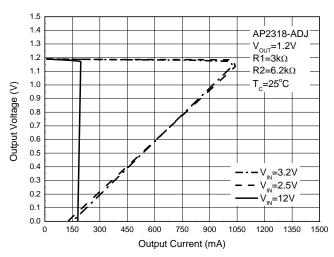
### Output Voltage vs. Output Current (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



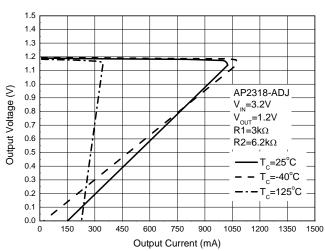
## Output Voltage vs. Output Current (Conditions: $V_{OUT} = 1.2V$ , $R1 = 3k\Omega$ , $R2 = 6.2k\Omega$ )



# Output Voltage vs. Output Current (Conditions: $V_{OUT}$ = 1.2V, R1 = $3k\Omega$ , R2 = $6.2k\Omega$ )

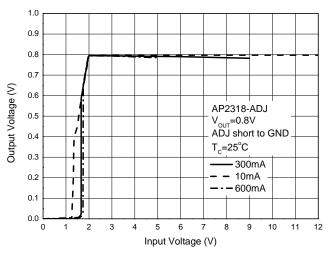


## Output Voltage vs. Output Current (Conditions: $V_{OUT} = 1.2V$ , $R1 = 3k\Omega$ , $R2 = 6.2k\Omega$ )

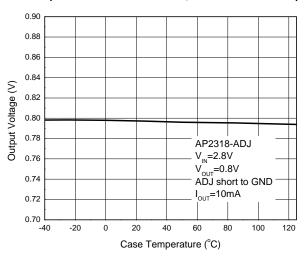




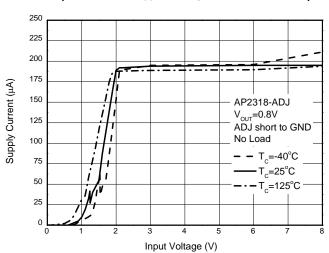
# Output Voltage vs. Input Voltage (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



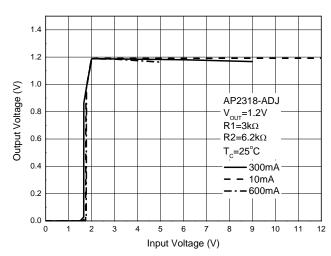
### Output Voltage vs. Case Temperature (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



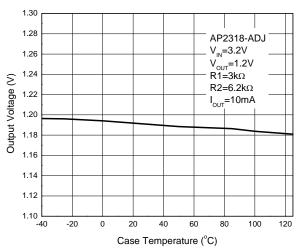
### Supply Voltage vs. Input Voltage (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



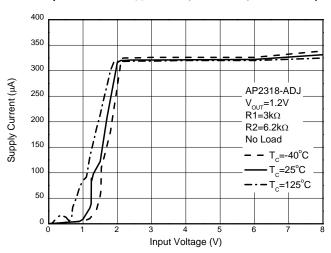
## Output Voltage vs. Input Voltage (Conditions: $V_{OUT} = 1.2V$ , $R1 = 3k\Omega$ , $R2 = 6.2k\Omega$ )



## Output Voltage vs. Case Temperature (Conditions: $V_{OUT} = 1.2V$ , R1 = $3k\Omega$ , R2 = $6.2k\Omega$ )

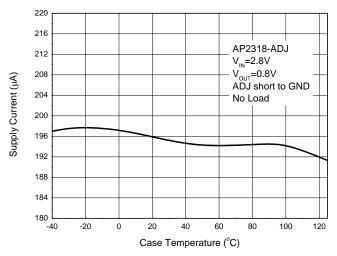


### Supply Voltage vs. Input Voltage (Conditions: $V_{OUT} = 1.2V$ , R1 = $3k\Omega$ , R2 = $6.2k\Omega$ )

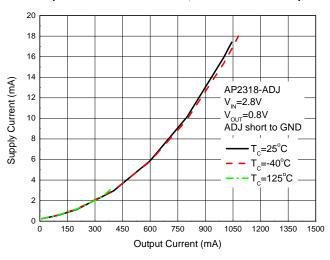




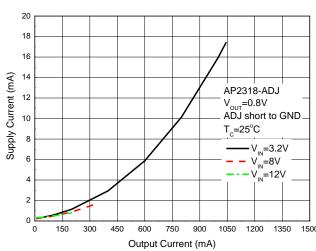
# Supply Current vs. Case Temperature (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



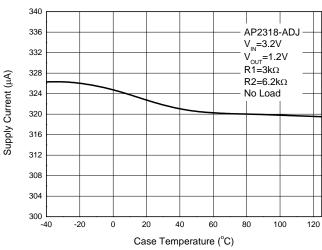
### Supply Current vs. Output Current (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



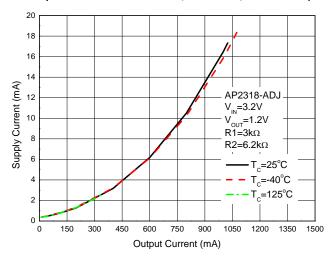
## Supply Current vs. Output Current (Conditions: V<sub>OUT</sub> = 0.8V, ADJ Short to GND)



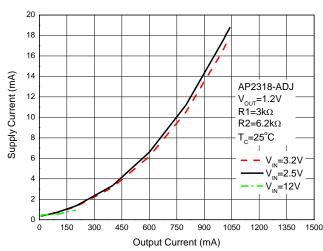
# Supply Current vs. Case Temperature (Conditions: $V_{OUT}$ = 1.2V, R1 = $3k\Omega$ , R2 = $6.2k\Omega$ )



### Supply Current vs. Output Current (Conditions: $V_{OUT} = 1.2V$ , R1 = $3k\Omega$ , R2 = $6.2k\Omega$ )

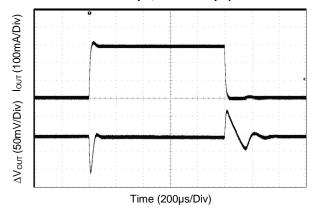


# Supply Current vs. Output Current (Conditions: $V_{OUT} = 1.2V$ , $R1 = 3k\Omega$ , $R2 = 6.2k\Omega$ )

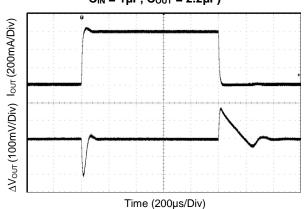




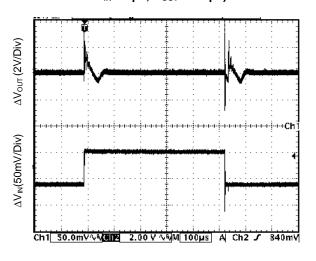
 $\label{eq:Load Transient Response} Load Transient Response \\ \mbox{(Conditions: $V_{IN}=2.5V$, $V_{OUT}=1.3V$, $I_{OUT}=1mA$ to $300mA$,} \\ \mbox{$C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$)}$ 



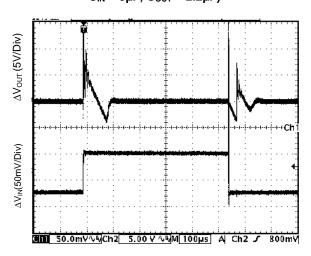
 $\label{eq:local_local_local} Load Transient Response \\ \mbox{(Conditions: $V_{IN}=2.5$V, $V_{OUT}=1.8$V, $I_{OUT}=1$mA to 600mA,} \\ \mbox{$C_{IN}=1$\mu F, $C_{OUT}=2.2$\mu F)} \\$ 



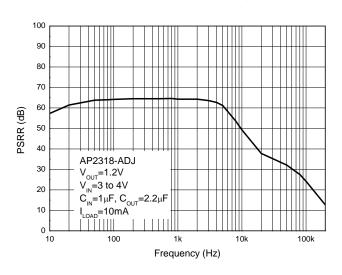
 $\label{eq:line_line_line} Line Transient Response \\ \mbox{(Conditions: $V_{IN}=2.5$V to 5$V$, $V_{OUT}=0.8$V$, $I_{OUT}=10$mA$,} \\ \mbox{$C_{IN}=0$\mu F$, $C_{OUT}=2.2$\mu F$)}$ 



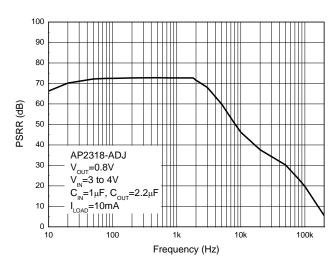
 $\label{eq:linear} Line \ Transient \ Response$  (Conditions: VIN = 2.5V to 10V, VOUT = 0.8V, IOUT = 10mA,  $C_{IN} = 0 \mu F, \ C_{OUT} = 2.2 \mu F)$ 



PSRR vs. Frequency

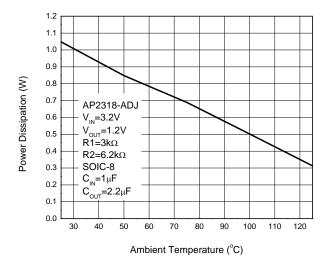


PSRR vs. Frequency

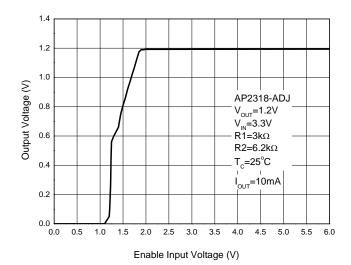




# Power Dissipation vs. Ambient Temperature (Conditions: $V_{OUT} = 1.2V$ , $R1 = 3k\Omega$ , $R2 = 6.2k\Omega$ )

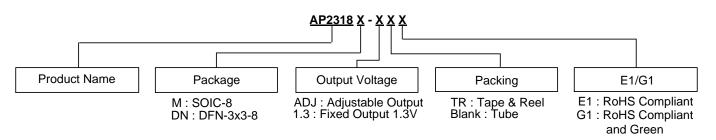


# Output Voltage vs. Enable Input Voltage (Conditions: $V_{OUT} = 1.2V$ , $R1 = 3k\Omega$ , $R2 = 6.2k\Omega$ )





#### **Ordering Information**

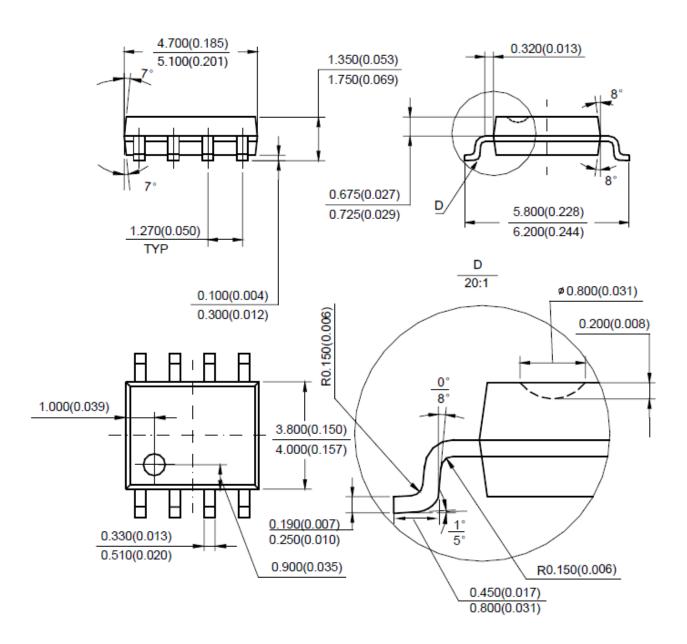


Package	Temperature Range	Part Number		Marking ID			
		RoHS Compliant	RoHS Compliant and Green	RoHS Compliant	RoHS Compliant and Green	Packing	
SOIC-8	-40 to +125°C	AP2318M-ADJE1	AP2318M-ADJG1	2318M-ADJE1	2318M-ADJG1	Tube	
		AP2318M- ADJTRE1	AP2318M-ADJTRG1	2318M-ADJE1	2318M-ADJG1	Tape & Reel	
		AP2318M-1.3E1	AP2318M-1.3G1	2318M-1.3E1	2318M-1.3G1	Tube	
		AP2318M- 1.3TRE1	AP2318M-1.3TRG1	2318M-1.3E1	2318M-1.3G1	Tape & Reel	
DFN-3x3-8	-40 to +125°C	AP2318DN- ADJTRE1	AP2318DN- ADJTRG1	F9E	B9E	Tape & Reel	
		AP2318DN- 1.3TRE1	AP2318DN- 1.3TRG1	F9B	B9B	Tape & Reel	



### Package Outline Dimensions (All dimensions in mm(inch).)

#### (1) Package Type: SOIC-8

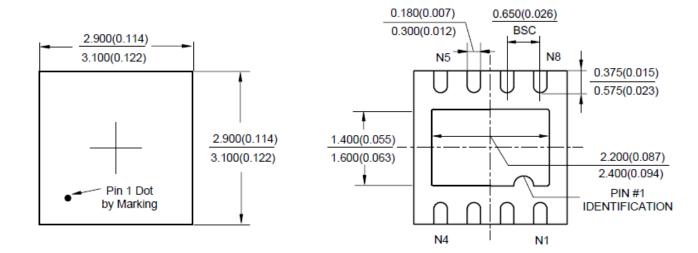


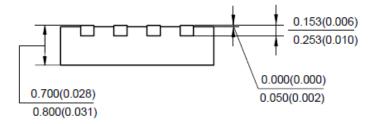
Note: Eject hole, oriented hole and mold mark is optional.



#### Package Outline Dimensions (Cont. All dimensions in mm(inch).)

#### (2) Package Type: DFN-3x3-8







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